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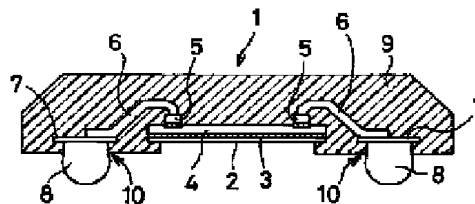
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**(54) SEMICONDUCTOR DEVICE AND LEAD FRAME
FOR ASSEMBLING THE SAME, AND
MANUFACTURE OF THE DEVICE**

(57) Abstract:

PROBLEM TO BE SOLVED: To provide a semiconductor device in which high reliability can be maintained, and high density can be attained with low costs, and a lead frame for assembling the semiconductor device, and a method for manufacturing a semiconductor device suited for down-sizing.

SOLUTION: A semiconductor 1 is constituted of a semiconductor element 4 whose back face a die pad 2 is connected through insulating adhesive 3 with, outside electrode pad 7 connected through a wire 6 with an inside electrode 5 of the semiconductor element 4, solder ball 8 connected with the outside electrode pad 7, and resin 9 sealing those parts. Then, in this semiconductor device 1, the solder ball 8 is exposed through an opening 10 formed in the resin 9 so as to be connectable with another substrate.



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